

(1,00mm) .03937"

MEC1 SERIES

MEC1-120-02-F-D-A

MEC1-130-02-F-D-A

MEC1-140-02-L-D

MINI EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over 50µ"

(1,27µm) Ni

Operating Temp Range:

-55°C to +125°C

Current Rating:

2A @ 80°C ambient

(See website for details)

Voltage Rating:

300 VAC

Insertion Depth:

(5,84mm) .230" to

(8,13mm) .320"

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

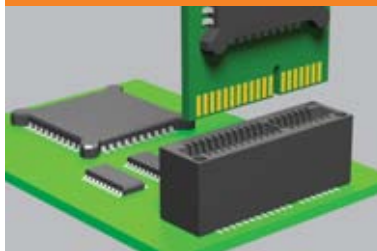
SMT Lead Coplanarity:

(0,10mm) .004" max (05-20)

(0,15mm) .006" max (30-70)

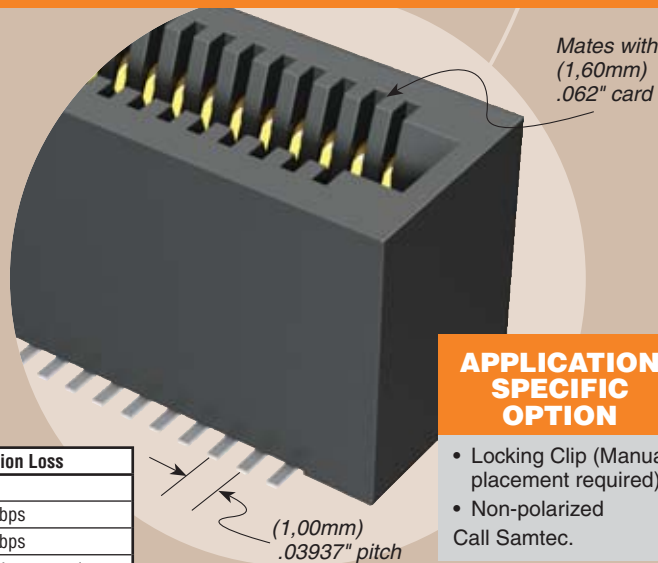
Mates with:
(1,60mm) .062" card

APPLICATION



1mm MEC1	Rated @ 3dB Insertion Loss
9,04mm Stack Height	
Single-Ended Signaling	5.5 GHz / 11 Gbps
Differential Pair Signaling	6.5 GHz / 13 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?MEC1 or contact sig@samtec.com



Mates with
(1,60mm) .062" card

APPLICATION SPECIFIC OPTION

- Locking Clip (Manual placement required).
- Non-polarized
Call Samtec.

MEC1

1

POSITIONS
PER ROW

02

PLATING
OPTION

D

OTHER
OPTION

05, 08, 20, 30, 40, 50, 60, 70

-F

= Gold flash on contact,
Matte tin on tail

-L

= 10µ" (0,25µm) Gold on contact,
Matte Tin on tail

-A

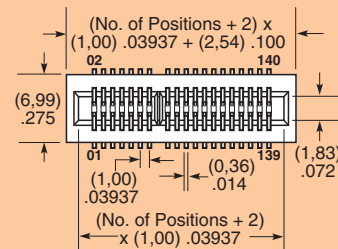
= Alignment
Pin metal or
plastic at
Samtec
discretion.

-K

= (7,87mm)
.310" DIA
Polyimide film
Pick &
Place Pad

-TR

= Tape & Reel



POSITIONS PER ROW	POLARIZED POSITIONS (No Contact)
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

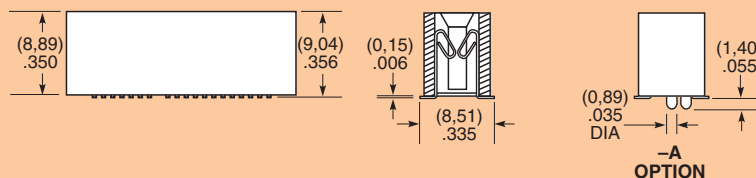
Important Note:

Samtec recommends that
pads on the mating board be
Gold plated.

Note:

Other Gold plating
options available.
Contact Samtec.

Note: Some sizes, styles and
options are non-standard,
non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM